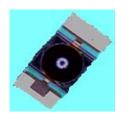


DATASHEET

1.6mm Round Subminiature Chip LED HIR26-21B/L423/CT



Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel
- Pb free
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH

Descriptions

- HIR26-21B/L423/CT is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens.
- The device is spectrally matched with silicon photodiode and phototransistor.

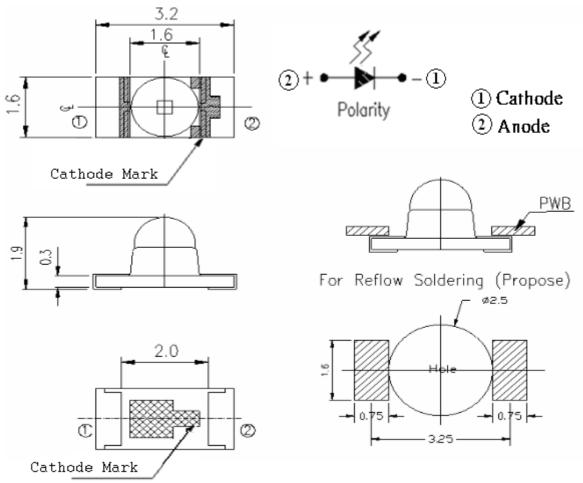
Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Scanner
- · Infrared applied system

Device Selection Guide

Part Category	Chip Material	Resin Color
HIR	GaAlAs	Black

Package Dimensions



Notes: 1.All dimensions are in millimeters

- 2. Tolerances unless dimensions ±0.1 mm
- 3.Suggested pad dimension is just for reference only

 Please modify the pad dimension based on individual need

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Units
- arameter	Cymber	- raung	
Continuous Forward Current	I _F	50	mA
Reverse Voltage	V_{R}	5	V
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}\! \mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\! \mathbb{C}$
Soldering Temperature *1	T_{sol}	260	$^{\circ}\! \mathbb{C}$
Power Dissipation at (or below) 25°C Free Air Temperature	P_d	130	mW

Notes: *1: Soldering time ≤ 5 seconds

Electro-Optical Characteristics (Ta=25°C)

Electro-Optical Characteristics (Ta=25 C)						
Parameter	Symbol	Condition	Min.	Тур.	Max.	Units
Radiant Intensity	le	I _F =20mA	10	20	1	mW/sr
Peak Wavelength	λр	I _F =20mA		850	1	nm
Spectral Bandwidth	Δλ	I _F =20mA		30		nm
Forward Voltage	V _F	I _F =20mA	1.20	1.45	1.70	V
Reverse Current	I _R	V _R =5V			10	μΑ
View Angle	201/2	I _F =20mA		20		deg

Radiant Intensity Specifications for Bin Grading

Rank	Test Condition	Min.	Max.	Units
R		10	15	
S		11	17	
Т		13	20	
U		15	23	
V	I _F =20mA	17	26	mW /sr
W		20	30	
Х		23	34	
Υ		26	40	
Z		>4	.0	

Notes: This bin table is only for reference, not for specific bin shipment.

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.

Ambient Temperature

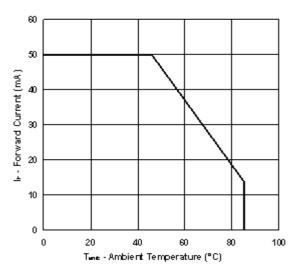


Fig.3 Forward Current vs. Forward Voltage

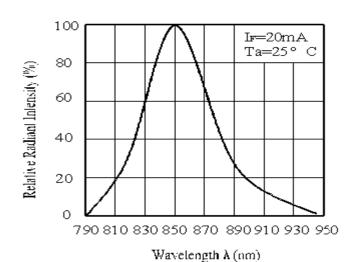
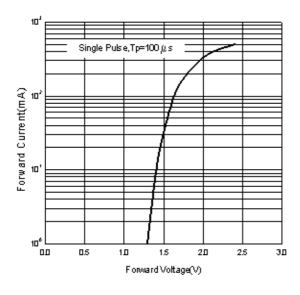
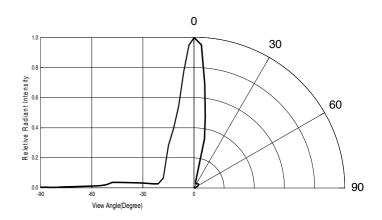


Fig.2 Spectral Distribution

Fig.4 Relative Radiant Intensity vs.

Angular Displacement





Precautions For Use

1. Over-current-proof

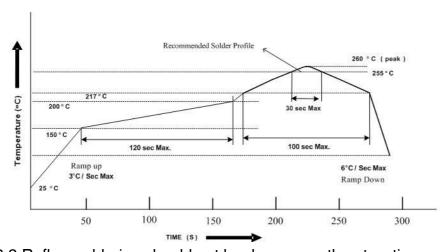
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 10°C ~30°C and 90%RH or less.
- 2.3 The LEDs suggested be used within one year.
- 2.4 After opening the package, the devices must be stored at 10°C~30°C and ≤ 60%RH, and used within 168 hours (floor life). If unused LEDs remain, it should be stored in moisture proof packages.
- 2.5 If the moisture absorbent material (desiccant material) has faded or unopened bag haexceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.
- 2.6 If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions:
 - 96 hours at 60° C ± 5° C and < 5° RH (reeled/tubed/loose units)

3. Soldering Condition

3.1 Pb-free solder temperature profile



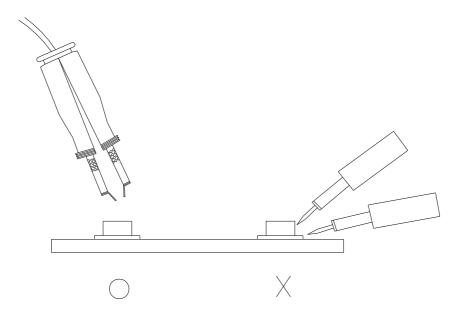
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

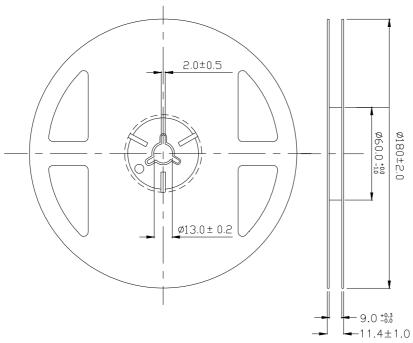
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

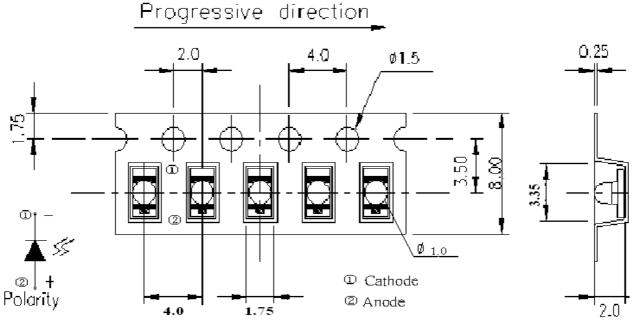


Package Dimensions



Note: The tolerances unless mentioned are ±0.1mm, Unit:mm

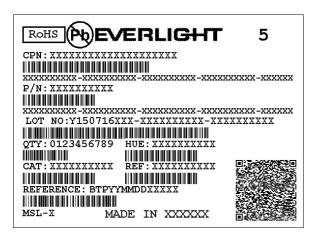
Carrier Taping Dimensions: Loaded Quantity 1500 PCS/Reel



Note: The tolerances unless mentioned are ±0.1mm, Unit:mm

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Label Form Specification



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number MSL-X: MSL Level

Made In: Manufacture place

Notes

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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EVERLIGHT ELECTRONICS CO., LTD.

Office: No. 6-8, Zhonghua Rd., Shulin Dist.,

New Taipei City 23860, Taiwan

Tel: 886-2-2685-6688

Fax: 886-2685-2699 , 6897

http://www.everlight.com